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**8A, 400V - 600V Hyperfast Diodes**

The RHRP840 and RHRP860 are hyperfast diodes with soft recovery characteristics ( $t_{rr} < 30ns$ ). They have half the recovery time of ultrafast diodes and are silicon nitride passivated ion-implanted epitaxial planar construction.

These devices are intended for use as freewheeling/clamping diodes and rectifiers in a variety of switching power supplies and other power switching applications. Their low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

Formerly developmental type TA49059.

**Ordering Information**

PART NUMBER	PACKAGE	BRAND
RHRP840	TO-220AC	RHRP840
RHRP860	TO-220AC	RHRP860

NOTE: When ordering, use the entire part number.

**Symbol**



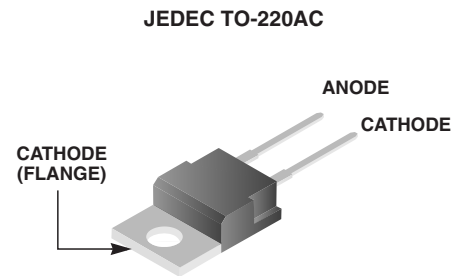
**Features**

- Hyperfast with Soft Recovery . . . . . <30ns
- Operating Temperature . . . . . 175°C
- Reverse Voltage Up To . . . . . 600V
- Avalanche Energy Rated
- Planar Construction

**Applications**

- Switching Power Supplies
- Power Switching Circuits
- General Purpose

**Packaging**



**Absolute Maximum Ratings**  $T_C = 25^\circ C$ , Unless Otherwise Specified

	RHRP840	RHRP860	UNITS
Peak Repetitive Reverse Voltage . . . . . $V_{RRM}$	400	600	V
Working Peak Reverse Voltage . . . . . $V_{RWM}$	400	600	V
DC Blocking Voltage . . . . . $V_R$	400	600	V
Average Rectified Forward Current . . . . . $I_{F(AV)}$ ( $T_C = 150^\circ C$ )	8	8	A
Repetitive Peak Surge Current . . . . . $I_{FRM}$ (Square Wave, 20kHz)	16	16	A
Nonrepetitive Peak Surge Current . . . . . $I_{FSM}$ (Halfwave, 1 Phase, 60Hz)	100	100	A
Maximum Power Dissipation . . . . . $P_D$	75	75	W
Avalanche Energy (See Figures 10 and 11) . . . . . $E_{AVL}$	20	20	mJ
Operating and Storage Temperature . . . . . $T_{STG}, T_J$	-65 to 175	-65 to 175	°C

# RHRP840, RHRP860

## Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

SYMBOL	TEST CONDITION	RHRP840			RHRP860			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
$V_F$	$I_F = 8\text{A}$	-	-	2.1	-	-	2.1	V
	$I_F = 8\text{A}, T_C = 150^\circ\text{C}$	-	-	1.7	-	-	1.7	V
$I_R$	$V_R = 400\text{V}$	-	-	100	-	-	-	$\mu\text{A}$
	$V_R = 600\text{V}$	-	-	-	-	-	100	$\mu\text{A}$
	$V_R = 400\text{V}, T_C = 150^\circ\text{C}$	-	-	500	-	-	-	$\mu\text{A}$
	$V_R = 600\text{V}, T_C = 150^\circ\text{C}$	-	-	-	-	-	500	$\mu\text{A}$
$t_{rr}$	$I_F = 1\text{A}, dI_F/dt = 200\text{A}/\mu\text{s}$	-	-	30	-	-	30	ns
	$I_F = 8\text{A}, dI_F/dt = 200\text{A}/\mu\text{s}$	-	-	35	-	-	35	ns
$t_a$	$I_F = 8\text{A}, dI_F/dt = 200\text{A}/\mu\text{s}$	-	18	-	-	18	-	ns
$t_b$	$I_F = 8\text{A}, dI_F/dt = 200\text{A}/\mu\text{s}$	-	10	-	-	10	-	ns
$Q_{RR}$	$I_F = 8\text{A}, dI_F/dt = 200\text{A}/\mu\text{s}$	-	56	-	-	56	-	nC
$C_J$	$V_R = 10\text{V}, I_F = 0\text{A}$	-	25	-	-	25	-	pF
$R_{\theta JC}$		-	-	2	-	-	2	$^\circ\text{C}/\text{W}$

### DEFINITIONS

$V_F$  = Instantaneous forward voltage ( $p_w = 300\mu\text{s}$ ,  $D = 2\%$ ).

$I_R$  = Instantaneous reverse current.

$t_{rr}$  = Reverse recovery time (See Figure 9), summation of  $t_a + t_b$ .

$t_a$  = Time to reach peak reverse current (See Figure 9).

$t_b$  = Time from peak  $I_{RM}$  to projected zero crossing of  $I_{RM}$  based on a straight line from peak  $I_{RM}$  through 25% of  $I_{RM}$  (See Figure 9).

$Q_{RR}$  = Reverse recovery charge.

$C_J$  = Junction capacitance.

$R_{\theta JC}$  = Thermal resistance junction to case.

$p_w$  = Pulse width.

$D$  = Duty cycle.

## Typical Performance Curves

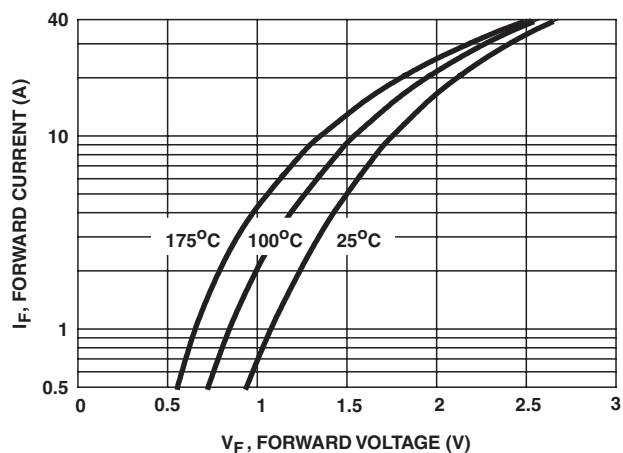


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

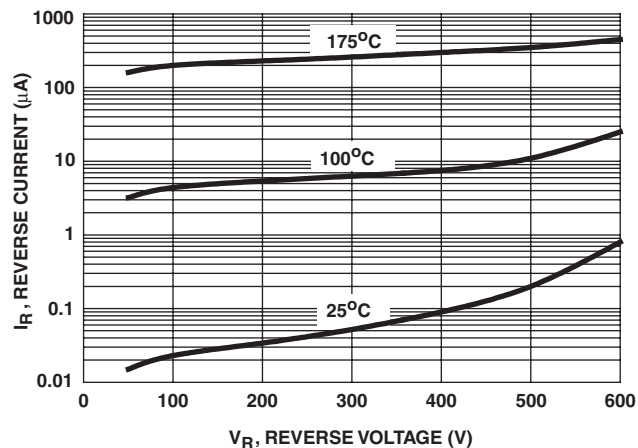


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

Typical Performance Curves (Continued)

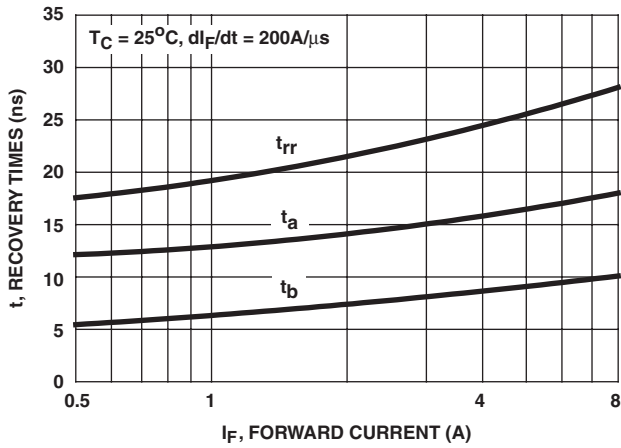


FIGURE 3.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

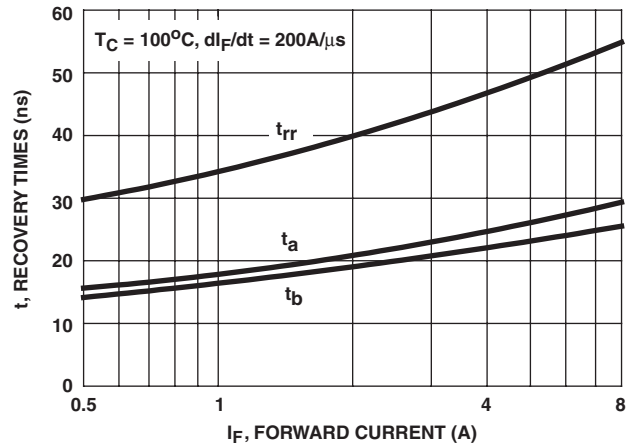


FIGURE 4.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

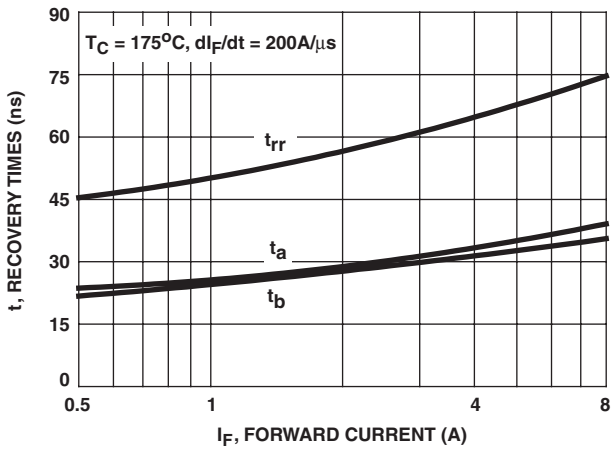


FIGURE 5.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

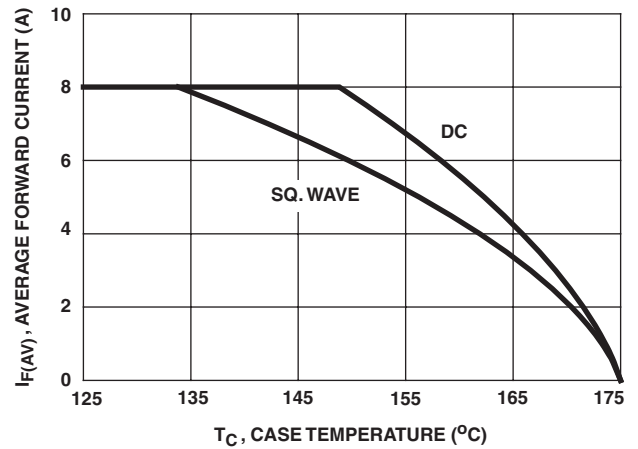


FIGURE 6. CURRENT DERATING CURVE

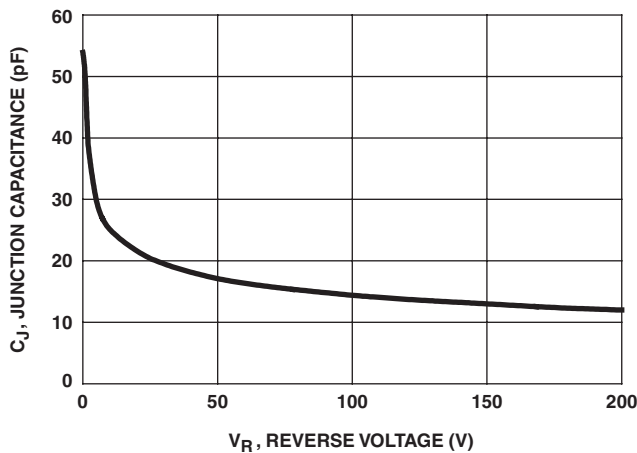


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

**Test Circuits and Waveforms**

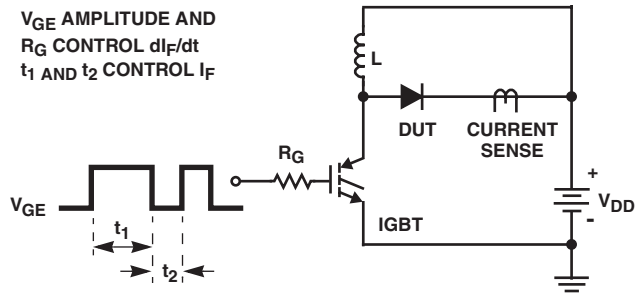


FIGURE 8.  $t_{rr}$  TEST CIRCUIT

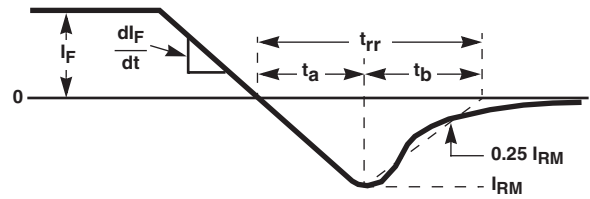


FIGURE 9.  $t_{rr}$  WAVEFORMS AND DEFINITIONS

$I_{MAX} = 1A$   
 $L = 40mH$   
 $R < 0.1\Omega$   
 $E_{AVL} = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$   
 $Q_1 = IGBT (BV_{CES} > DUT V_{R(AVL)})$

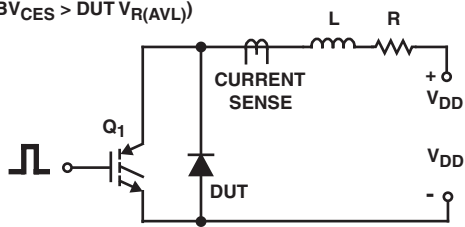


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

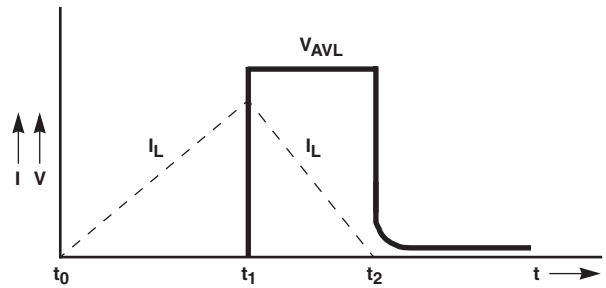


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS



NOTES:

- A. PACKAGE REFERENCE: JEDEC TO220,ISSUE K, VARIATION AC,DATED APRIL 2002.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DRAWING FILE NAME: TO220A02REV5

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